

1 ABSTRACT OF THE DISCLOSURE

2 A semiconductor workpiece holder for use in processing a
3 semiconductor workpiece includes a workpiece support operatively
4 mounted to support a workpiece in position for processing. A finger
5 assembly is operatively mounted upon the workpiece support and
6 includes a finger tip. The finger assembly is movable between an
7 engaged position in which the finger tip is engaged against the
8 workpiece, and a disengaged position in which the finger tip is moved
9 away from the workpiece. Preferably, at least one electrode forms part
10 of the finger assembly and includes an electrode contact for contacting
11 a surface of said workpiece. At least one protective sheath covers at
12 least some of the electrode contact. According to one aspect of the
13 invention, a sheathed electrode having a sheathed electrode tip is
14 positioned against a semiconductor workpiece surface in a manner
15 engaging the workpiece surface with said sheathed electrode tip. A seal
16 is formed about the periphery of the electrode tip, and with the
17 electrode tip engaging the workpiece, a desired electrical contact is
18 made to the workpiece. Thereafter, the workpiece is exposed to
19 desired semiconductor processing conditions.
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